

ABSTRACT OF THE DISCLOSURE

An MCM package with bridge connection mainly comprises a carrier, a first chip, a second chip and at least one conductive body. The carrier has an upper surface and an opposite lower surface, and a plurality of contacts formed on the upper surface of the carrier. The first chip has a first active surface, a first side surface and a first bonding pad formed on the first active surface. Similarly, the second chip has a second active surface, a second side surface, and a second bonding pad formed on the second active surface. Therein, the first side surface of the first chip is proximate to the second side surface of the second chip, and the first active surface is coplanar to the second active surface. Accordingly, one of the conductive body can be disposed continuously on the active surface and the second surface to electrically connect the first chip and the second chip.